

What Is Claimed Is:

1. A method of manufacturing a mounting substrate accommodating therein an electronic component for use in a surface mount crystal oscillator and adapted to be joined to a bottom surface of a crystal unit, comprising the steps of:

5 **defining a recess with a bottom wall and a frame wall having an opening;**

placing the electronic component in said recess;

filling said recess with a resin for protecting said electronic component; and

10 **after said resin is cured, removing at least a portion of said frame wall.**

2. The method according to claim 1, wherein said mounting substrate has a substantially rectangular planar shape, and said frame wall is removed along a pair of longer sides of said mounting substrate.

3. The method according to claim 1, wherein said electronic component comprises an IC chip.

4. A method of manufacturing a mounting substrate accommodating therein an electronic component for use in a surface mount crystal oscillator and adapted to be joined to a bottom surface of a crystal unit, comprising the steps of:

5 **laminating a bottom wall sheet and a frame wall sheet having a plurality of openings defined therein, thereby producing a sheet substrate;**

placing electronic components in recesses which are provided by said openings, respectively;

filling said recesses with a resin for protecting said electronic
10 components; and

after said resin is cured, severing said sheet substrate at least in positions where said resin is provided, into mounting substrates each with at least a portion of a frame wall which surrounds said recess being removed.

5. The method according to claim 4, wherein said sheet substrate is formed by baking.

6. The method according to claim 4, wherein each of said mounting substrates has a substantially rectangular planar shape, and said sheet substrate is severed to remove said frame wall along a pair of longer sides of said mounting substrate.

7. The method according to claim 4, wherein said electronic components comprise IC chips.

8. A method of manufacturing a mounting substrate accommodating therein an electronic component for use in a surface mount crystal oscillator and adapted to be joined to a bottom surface of a crystal unit, comprising the steps of:

5 laminating a bottom wall sheet and a frame wall sheet having a plurality of elongate openings defined therein, thereby producing a sheet substrat ;

placing electronic components in grooves which are provided by said openings;

10 filling said grooves with a resin for protecting said electronic components; and

after said resin is cured, severing said sheet substrate including said resin in positions between adjacent ones of said electronic components, into mounting substrates.

9. The method according to claim 8, wherein said sheet substrate is formed by baking.

10. The method according to claim 8, wherein said electronic components comprise IC chips.

11. A surface mount crystal oscillator comprising:

a crystal unit; and

a mounting substrate manufactured by a method according to claim 1 and joined to a bottom surface of said crystal unit.

12. A surface mount crystal oscillator comprising:

a crystal unit; and

a mounting substrate manufactured by a method according to claim 4 and joined to a bottom surface of said crystal unit.

13. A surface mount crystal oscillator comprising:

a crystal unit; and

a mounting substrate manufactured by a method according to claim 8
and joined to a bottom surface of said crystal unit.